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DRILL CHART: TOP to BOTTOM

(ALL UNITS ARE IN MILLIMETERS)

FIGURE	SIZE	TOLERANCE	PLATED	QTY
+	0.200	+0.100/-0.200	PLATED	484
□	0.500	+0.100/-0.100	PLATED	3
○	1.000	+0.100/-0.100	PLATED	154
	1.600	+0.100/-0.100	PLATED	10
◇	3.200	+0.100/-0.000	PLATED	4
⊗	0.850x0.650	+0.050/-0.050	PLATED	4
⊙	1.300x0.600	+0.050/-0.050	PLATED	4
TOTAL HOLES:				663

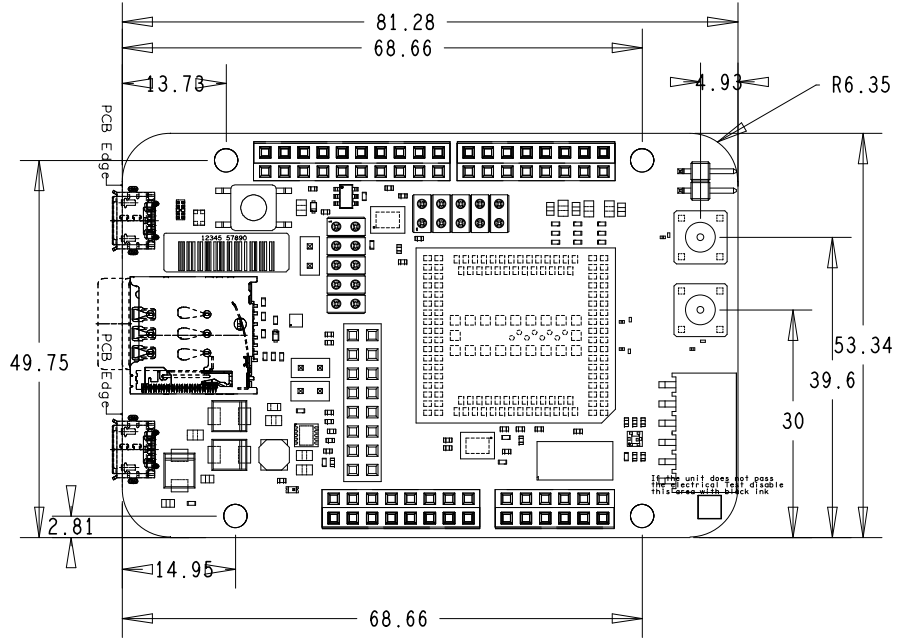
final copper thickness on all layers: 35um

Base Material Core	FR4 UL Conform 94V-0
Base Material Prepreg	FR4 UL Conform 94V-0
required Thickness	1.6mm +/- 10% (metal-to-metal)
Standards	IPC-A-600(*) Class2 / PERFAQ3(*) *newest Version
SILKSCREEN_TOP	Silkscreen color YELLOW or WHITE Line width Impedance
SOLDERMASK_TOP	Ni 2.5-6um / im. Au 0.05-0.125um
TOP	Cu S >17um 200um 50ohm +/-10%
GND1	Prepreg 150um
	Cu P 35 um PLANE
PWR1	CORE 1100um
	Prepreg 150um
BOT	Cu S >17um 200um 50ohm +/-10%
SOLDERMASK_BOT	SOLDERMASK max. 50um (GREEN)

(calculated stackup thickness: 1540um metal-to-metal)

DIFFERENTIAL IMPEDANCE

90 OHM			
LAYER	WIDTH	PRIMARY GAP	REF. PLANE
TOP/BOT	200um	200um	PWR1 / PWR2



Via plugging:

- If no soldermask opening on any side: Plug all Vias per **IPC4761 Type VI-b**
- If soldermask opening on one side only: Please contact us to clarify. Except: please plug all vias-in-pad (cooling pad, e.g.:)
- If soldermask opening on both sides: No filling needed. Microvias only (if present): Please use copperfill

For all holes $\leq 0,5\text{mm}$

Design	AVT Cellular Shield	Designed	02.06.2016	SMOR
Layer	WASSEMBLIMEMORONS	Checked	02.02.2016	PAH
File Name	LY2012437.brd	Approved	02.06.2016	OWE
Mat. No.	69178	Changed	xx.xx.201X	XXXX
Sheet	29	Revision	2.0	03 Logout Version 02 Netlist Version
Scale	Fit to page			
Doc. No.	69178/29			